

VIGON® EFM

Precision cleaning medium for manual flux removal



VIGON® EFM is a precision cleaning agent designed to remove flux residues from electronic assemblies in manual applications. This product can also be used in ex-proofed, spray-in-air equipment. VIGON® EFM is a mixture of halogen-free, organic solvents. It dries fast and residue-free. VIGON® EFM is non-corrosive and compatible with most polymers.

Areas of application: PCB's		Further information on this product:
Resin-based flux residues*	++	Technical Information sheet 3: Overview regarding material compatibility
Low solid flux residues*	o	
Water soluble flux residues*	-	

++ highly recommended, best results + recommended o possible - not recommended
* Apply for all standard, lead-free and eutectic solder pastes

Free-of-Charge Cleaning Trials & Surface Analytics at ZESTRON's Technical Centers



Free-of-charge cleaning trials can be performed at one of ZESTRON's Global Technical Centers. ZESTRON's European, North American and Asian Technical Centers feature spray-in-air, ultrasonic or spray-under-immersion processes. This provides an extensive overview on all available processes by leading international equipment manufacturers.



Upon completion of the cleaning trials, extensive analytical tests such as SIR and ionic residue measurements can be performed.

Please consult with ZESTRON's Application Technology Centers regarding future cleaning trials: Phone +49-841-635-140; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- VIGON® EFM is especially suited for the removal of resin-based flux residues.
- This product dries very fast and residue-free by air exposure.
- VIGON® EFM is easy-to-use.
- It can be used for both manual and automatic cleaning in ex-proofed equipment.
- Very suitable as a cleaning and rinsing agent.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.



Process	Cleaning	Rinsing	Drying
Spray-in-air	VIGON® EFM	VIGON® EFM	Compressed air or open air
Manual cleaning	VIGON® EFM	VIGON® EFM	Compressed air or open air

Technical Data		
Density	(g/ccm) at 20°C/68°C	0.72
Surface tension	(mN/m) at 25°C/77°F	18.6
Boiling range	°C/°F	78 - 120 / 172 - 248
Flash point	°C/°F	-12 / 10
pH-Value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 77
Solubility in water		Not Soluble
Cleaning temperature		ambient Temperature
Application concentration	Ready to use	Pure
HMIS Rating	Health-Flammability-Reactivity	1 - 4 - 0

LEAD-FREE COMPLIANT



VIGON® EFM meets the new RoHS & WEEE guidelines as well as current worker safety standards and the actual applicable environmental requirements. ZESTRON voluntarily avoids the use of critical substances at product development.



Extensive tests confirmed the qualification of VIGON® EFM for the removal of fluxes lead-free solder pastes.

Environmental, health and safety regulations:

VIGON® EFM is a biodegradable. It is a highly flammable cleaning medium.

Availability/Storage:

VIGON® EFM is available as an easy-to-use aerosol can with detachable brush for manual removal of flux residues. It is also available in 1L, 25L, 55L and 200L containers.

Store VIGON® EFM in the original container at a temperature between 5°C - 30°C / 41 - 86°F. The product has a minimum shelf life of 5 years in factory sealed containers.



Alternative product recommendation:

For the manual removal of SMT adhesive we recommend ZESTRON® HC.

ZESTRON®

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